

DATA SHEET

74AVC16374; 74AVCH16374 16-bit edge triggered D-type flip-flop; 3-state

Objective specification
File under Integrated Circuits, IC24

1998 Dec 11

**16-bit edge triggered D-type flip-flop;
3-state**

**74AVC16374;
74AVCH16374**

FEATURES

- Wide supply voltage range of 1.2 V to 3.6 V
- Complies with JEDEC standard no. 8-1A/5/7
- CMOS low power consumption
- Input/Output tolerant up to 3.6 V
- DCO (Dynamic Controlled Output) Circuit dynamically changes output impedance, resulting in noise reduction without speed degradation
- Low inductance multiple V_{CC} and GND pins for minimize noise and ground bounce.
- All data inputs have bushold. (only 74AVCH16374)
- Power off disables 74AVC16374; 74AVCH16374 outputs, permitting Live Insertion.

DESCRIPTION

The 74AVC(H)16374 is a 16-bit edge triggered flip-flop featuring separate D-type inputs for each flip-flop and 3-State outputs for bus oriented applications. Incorporates bushold data inputs which eliminate the need for external pull-up resistors to hold unused inputs.

This product is designed to have an extremely fast propagation delay and a minimum amount of power consumption.

To ensure the high-impedance output state during power up or power down, \overline{OE}_n should be tied to V_{CC} through a pullup resistor (Live insertion).

A Dynamic Controlled Output (DCO) circuitry is implemented to support termination line drive during transient. See graphs at this page for typical curves.

The 74AVCH16374 consist of 2 sections of eight edge-triggered flip-flops. A clock (CP) input and an output enable (\overline{OE}) are provided per 8-bit section

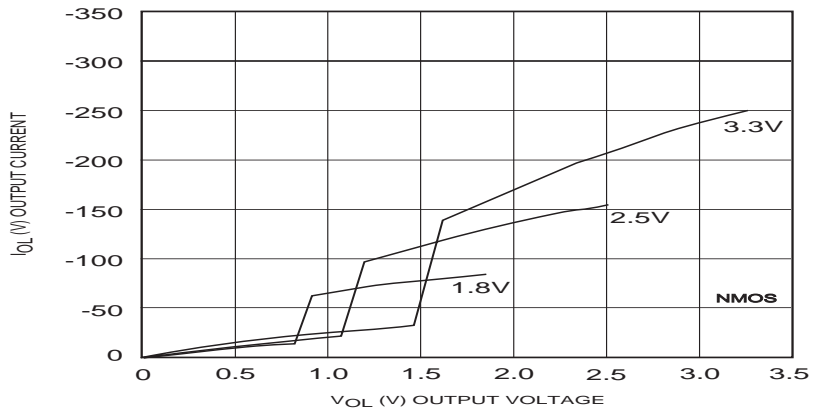
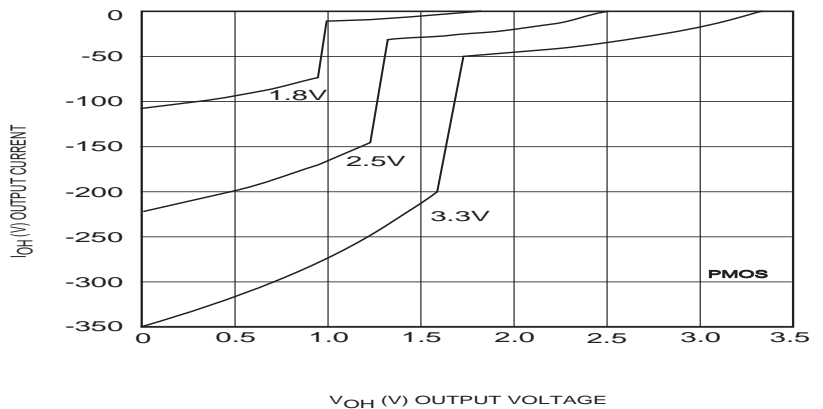
QUICK REFERENCE DATA

GND = 0 V; T_{amb} = 25 °C; t_r = t_f ≤ 2.0 ns; C_L = 30 pF.

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t _{PHL} / t _{PLH}	propagation delay CP to Q _n	V _{CC} = 1.8 V	1.9	ns
		V _{CC} = 2.5 V	1.4	ns
		V _{CC} = 3.3 V	1.2	ns
F _{max}	maximum clock frequency	V _{CC} = 1.8 V ⁽³⁾	320	MHz
		V _{CC} = 2.5 V ⁽³⁾	400	MHz
		V _{CC} = 3.3 V ⁽³⁾	500	MHz
C _I	input capacitance		5.0	pF
C _{PD}	power dissipation capacitance per buffer	notes 1 and 2 outputs enabled	22	pF
		output disabled	5	pF

Notes

1. C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
 $P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$ where:
 f_i = input frequency in MHz;
 f_o = output frequency in MHz;
 C_L = output load capacitance in pF;
 V_{CC} = supply voltage in V;
 $\sum (C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.
2. The condition is V_I = GND to V_{CC}.
3. For type with bushold.



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74AVC16374; 74AVCH16374

FUNCTION TABLE

See Note 1.

OPERATING MODES	INPUTS			INTERNAL FLIP-FLOPS	OUTPUT
	\overline{OE}	CP	Dn		nY
Load and read register	L	↑	L	L	L
(Hold mode)	L	↑	h	H	H
Load register and disable outputs	H	↑	l	L	Z
	H	↑	h	H	Z

Note

- H - HIGH voltage level;
h - HIGH voltage level one set-up time prior to the LOW-to-HIGH CP transition;
L - LOW voltage level;
l - LOW voltage level one set-up time prior to the LOW-to-HIGH CP transition;
X- don't care;
Z - high impedance OFF-state;
↑- LOW-to-HIGH CP transition

ORDERING AND PACKAGE INFORMATION

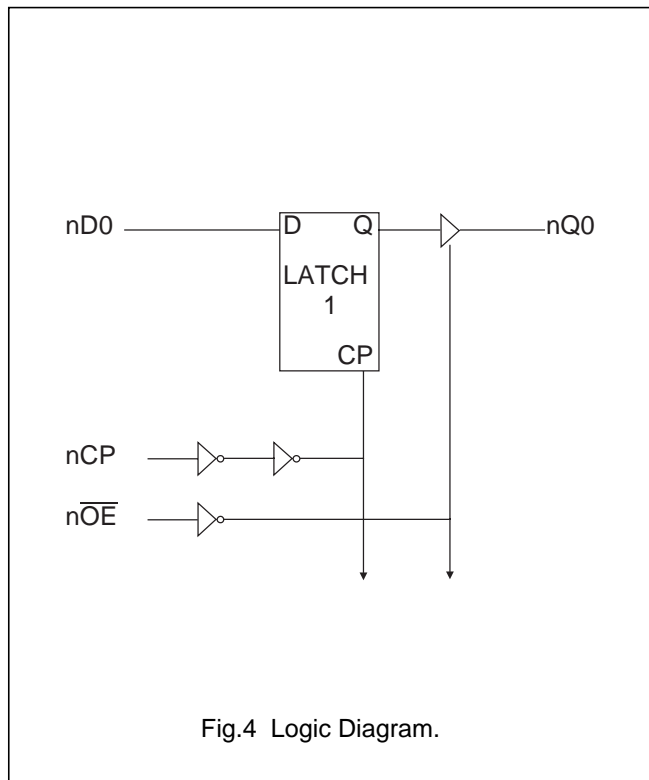
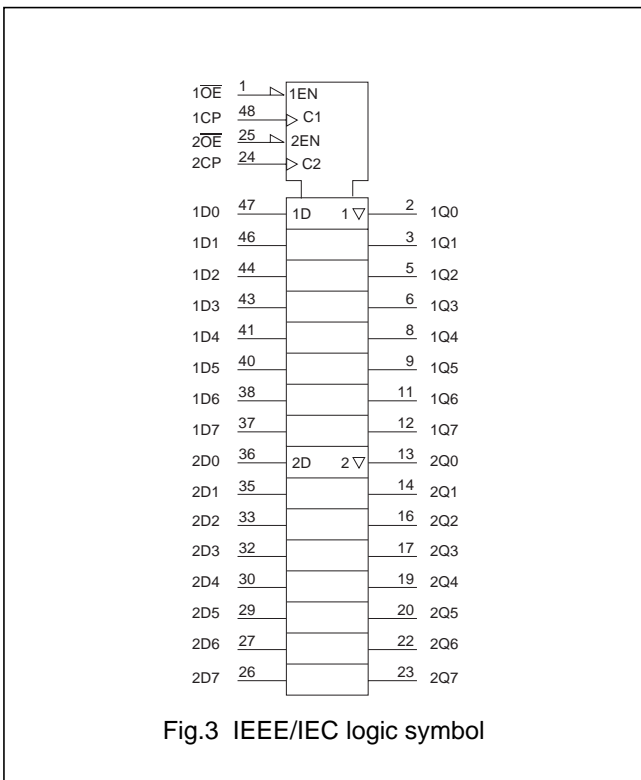
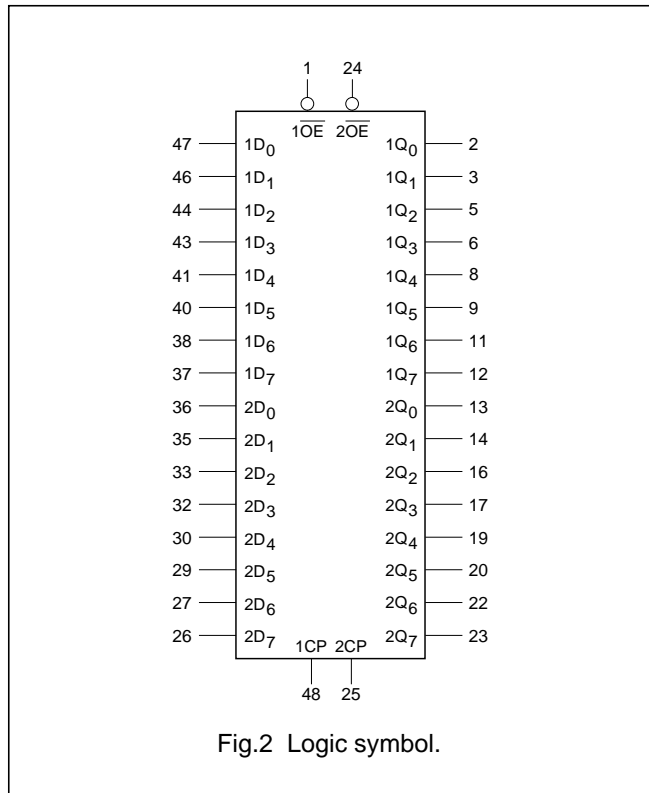
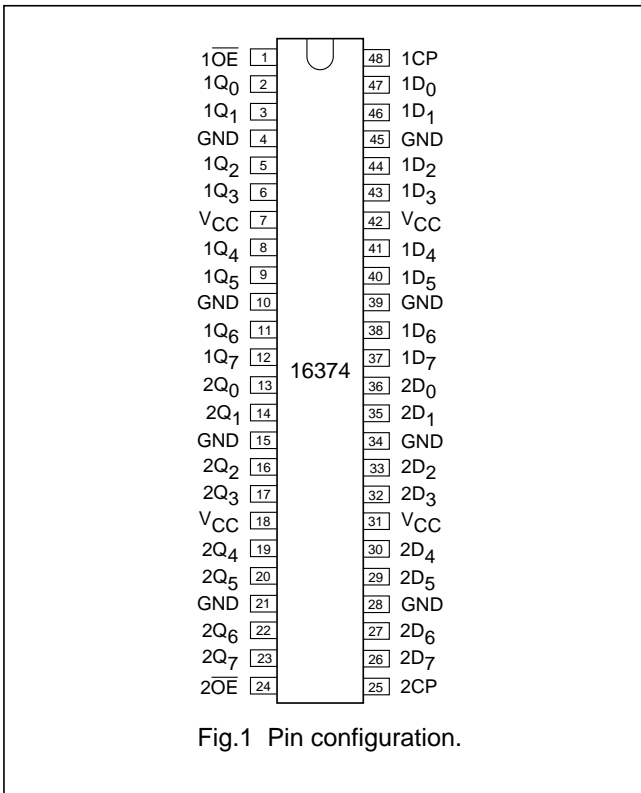
OUTSIDE NORTH AMERICA	NORTH AMERICA	PACKAGES				
		TEMPERATURE RANGE	PINS	PACKAGE	MATERIAL	CODE
74AVC16374DGG		-40 to +85 °C	48	TSSOP	plastic	SOT362-1
74AVCH16374DGG		-40 to +85 °C	48	TSSOP	plastic	SOT362-1

PINNING

PIN	SYMBOL	DESCRIPTION
1	$1\overline{OE}$	Output enable input (active LOW)
2, 3, 5, 6, 8, 9, 11 and 12	1Q ₀ to 1Q ₇	3-state flip-flop outputs
4, 10, 15, 21, 28, 34, 39 and 45	GND	Ground (0 V)
7, 18, 31 and 42	V _{CC}	Positive supply voltage
13, 14, 16, 17, 19, 20, 22 and 23	2Q ₀ to 2Q ₇	3-state flip-flop outputs
24	$2\overline{OE}$	Output enable input (active LOW)
25	2CP	Clock input
36, 35, 33, 32, 30, 29, 27 and 26	2D ₀ to 2D ₇	Data inputs
47, 46, 44, 43, 41, 40, 38 and 37	1D ₀ to 1D ₇	Data inputs
48	1CP	Clock input

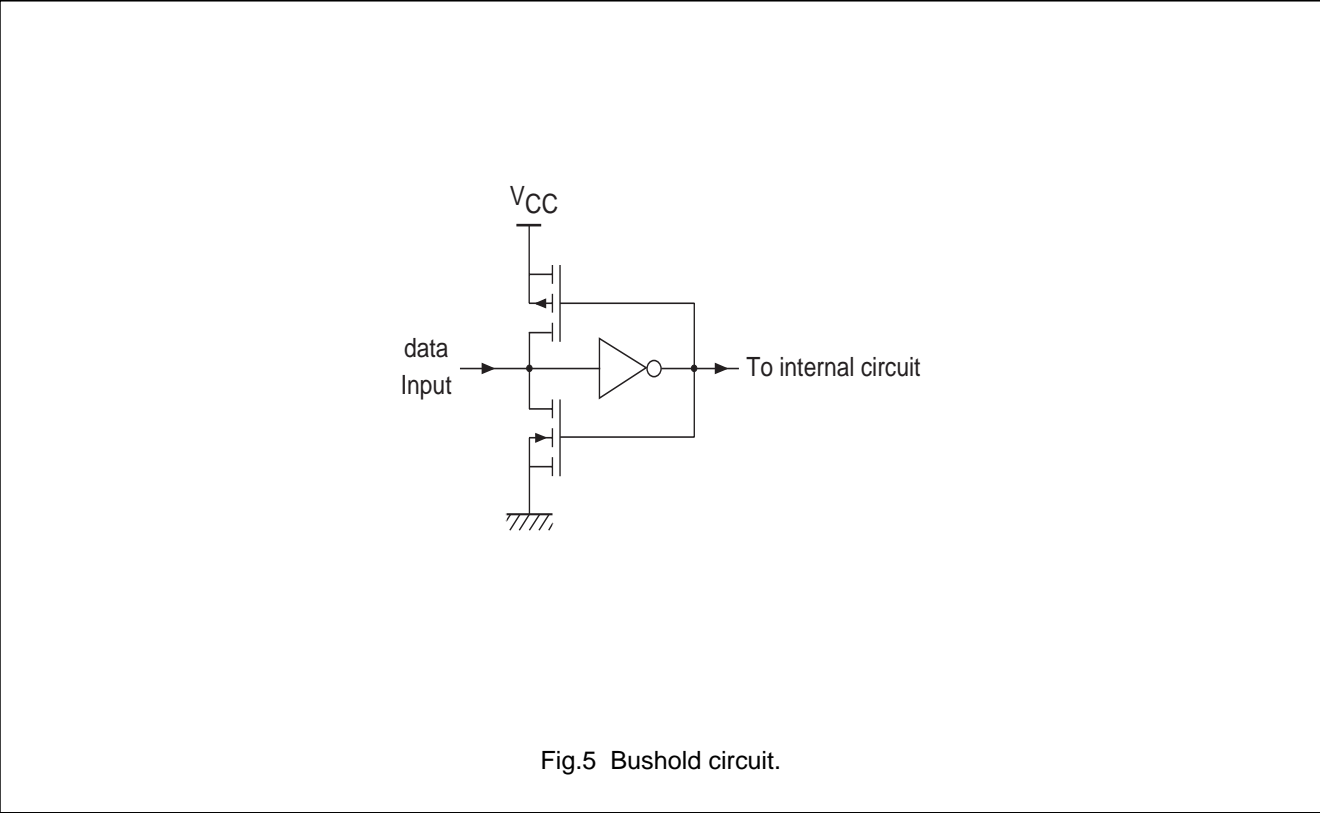
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RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CC}	DC supply voltage According to JEDEC Low Voltage Standards		1.65	1.95	V
			2.3	2.7	V
			3.0	3.6	V
V _{CC}	DC supply voltage (for low-voltage applications)		1.2	3.6	V
V _I	DC input voltage range		0	3.6	V
V _O	DC output voltage range; output 3-state		0	3.6	V
V _O	DC output voltage range; output High or Low state		0	V _{CC}	V
T _{amb}	operating ambient temperature range	in free air	-40	+85	°C
t _r , t _f	input rise and fall times	V _{CC} = 1.65 to 2.3 V	0	30	ns/V
		V _{CC} = 2.3 to 3.0 V	0	20	ns/V
		V _{CC} = 3.0 to 3.6 V	0	10	ns/V

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134). Voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CC}	DC supply voltage		-0.5	+4.6	V
I _{IK}	DC input diode current	V _I < 0	-	-50	mA
V _I	DC input voltage	for inputs; note 1	-0.5	4.6	V
I _{OK}	DC output diode current	V _O > V _{CC} or V _O < 0	-	±50	mA
V _O	DC output voltage; output High or Low state	note 1	-0.5	V _{CC} + 0.5	V
V _O	DC output voltage; output 3-state	note 1	-0.5	4.6	V
I _O	DC output source or sink current	V _O = 0 to V _{CC}	-	±50	mA
I _{GND} , I _{CC}	DC V _{CC} or GND current		-	±100	mA
T _{stg}	storage temperature range		-65	+150	°C
P _{tot}	power dissipation per package	for temperature range: -40 to +125 °C			
	plastic thin-medium-shrink (TSSOP)	above +55 °C derate linearly with 8 mW/K	-	600	mW

Notes

- The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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74AVC16374; 74AVCH16374

DC CHARACTERISTICS

Over recommended operating conditions. Voltage are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	$T_{amb} = -40 \text{ TO } +85 \text{ } ^\circ\text{C}$			UNIT	TEST CONDITIONS		
		MIN.	TYP. ⁽¹⁾	MAX.		V_{CC} (V)	V_I (V)	OTHER
V_{IH}	HIGH level input voltage	V_{CC}	–	–	V	1.2		
		$0.65V_{CC}$	0.9	–	V	1.65 to 1.95		
		1.7	1.2	–	V	2.3 to 2.7		
		2.0	1.5	–	V	3.0 to 3.6		
V_{IL}	LOW level input voltage	–	–	GND	V	1.2		
		–	0.9	$0.35V_{CC}$	V	1.65 to 1.95		
		–	1.2	0.7	V	2.3 to 2.7		
		–	1.5	0.8	V	3.0 to 3.6		
V_{OH}	HIGH level output voltage	$V_{CC}-0.20$	V_{CC}	–	V	1.65 to 3.6	V_{IH} or V_{IL}	$I_O = -100 \mu\text{A}$
		$V_{CC}-0.45$	$V_{CC}-0.10$	–	V	1.65		$I_O = -4 \text{ mA}$
		$V_{CC}-0.55$	$V_{CC}-0.28$	–	V	2.3		$I_O = -8 \text{ mA}$
		$V_{CC}-0.70$	$V_{CC}-0.32$	–	V	3.0		$I_O = -12 \text{ mA}$
V_{OL}	LOW level output voltage	–	GND	0.20	V	1.65 to 3.6	V_{IH} or V_{IL}	$I_O = 100 \mu\text{A}$
		–	0.10	0.45	V	1.65		$I_O = 4 \text{ mA}$
		–	0.26	0.55	V	2.3		$I_O = 8 \text{ mA}$
		–	0.36	0.70	V	3.0		$I_O = 12 \text{ mA}$
I_I	input leakage current per pin	–	0.1	2.5	μA	1.65 to 3.6	V_{CC} or GND	
I_{OFF}	power off leakage current	–	0.1	± 10	μA	0		V_I or $V_O = 3.6$
I_{IHZ}/I_{ILZ}	input current for common I/O pins	–	0.1	12.5	μA	1.65 to 3.6	V_{CC} or GND	
I_{OZ}	3-state output OFF-state current	–	0.1	5	μA	1.65 to 2.7	V_{IH} or V_{IL}	$V_O = V_{CC}$ or GND
		–	0.1	10	μA	3.0 to 3.6		
I_{CC}	quiescent supply current	–	0.1	20	μA	1.65 to 2.7	V_{CC} or GND	$I_O = 0$
		–	0.2	40	μA	3.0 to 3.6		

Note

1. All typical values are measured at $T_{amb} = 25 \text{ } ^\circ\text{C}$.

OPTIONAL: BUSHOLD SPECIFICATION FOR 74AVCH16374 ONLY

DC CHARACTERISTICS

Over recommended operating conditions. Voltage are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	$T_{amb} = -40 \text{ TO } +85 \text{ } ^\circ\text{C}$			UNIT	TEST CONDITIONS		
		MIN.	TYP. ⁽¹⁾	MAX.		V_{CC} (V)	V_I (V)	OTHER
I_{BHL}	bushold LOW sustaining current	25	–	–	μA	1.65	$0.35V_{CC}$	see note 2.
		45	–	–	μA	2.3	0.7 V	
		75	–	–	μA	3.0	0.8 V	

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3-state**
**74AVC16374;
74AVCH16374**

SYMBOL	PARAMETER	$T_{amb} = -40 \text{ TO } +85 \text{ } ^\circ\text{C}$			UNIT	TEST CONDITIONS		
		MIN.	TYP. ⁽¹⁾	MAX.		V_{CC} (V)	V_I (V)	OTHER
I_{BHH}	bushold HIGH sustaining current	-25	-	-	μA	1.65	$0.65V_{CC}$	see note 2.
		-45	-	-	μA	2.3	1.7 V	
		-75	-	-	μA	3.0	2.0 V	
I_{BHLO}	bushold LOW overdrive current	200	-	-	μA	1.95		see note 2.
		300	-	-	μA	2.7		
		450	-	-	μA	3.6		
I_{BHHO}	bushold HIGH overdrive current	-200	-	-	μA	1.95		see note 2.
		-300	-	-	μA	2.7		
		-450	-	-	μA	3.6		

Note

1. All typical values are measured at $T_{amb} = 25 \text{ } ^\circ\text{C}$.
2. Valid for data inputs of bushold parts.

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74AVC16374; 74AVCH16374

AC CHARACTERISTICS 74AVC16374

GND = 0 V; $t_r = t_f \leq 2.0$ ns; $C_L = 30$ pF.

SYMBOL	PARAMETER	$T_{amb} = -40$ to $+85$ °C			UNIT	TEST CONDITIONS	
		MIN.	TYP. ⁽¹⁾	MAX.		V_{CC} (V)	WAVEFORMS
t_{PHL}/t_{PLH}	propagation delay nCP to nQ _n	1.6	3.2	5.5	ns	1.2	see Fig.6, Fig.9
		0.9	2.0 ⁽²⁾	4.0	ns	1.65 to 1.95	
		0.8	1.4 ⁽²⁾	2.5	ns	2.3 to 2.7	
		0.7	1.2 ⁽²⁾	2.2	ns	3.0 to 3.6	
t_{PZH}/t_{PZL}	3-state output enable time \overline{nOE}_n to nQ _n	–	5.0	–	ns	1.2	see Fig.8, Fig.9
		1.6	3.0 ⁽²⁾	5.5	ns	1.65 to 1.95	
		1.3	2.1 ⁽²⁾	4.5	ns	2.3 to 2.7	
		1.2	1.8 ⁽²⁾	4.0	ns	3.0 to 3.6	
t_{PHZ}/t_{PLZ}	3-state output disable time \overline{nOE}_n to nQ _n	–	5.0	–	ns	1.2	see Fig.8, Fig.9
		2.2	3.5 ⁽²⁾	5.0	ns	1.65 to 1.95	
		1.1	1.8 ⁽²⁾	4.0	ns	2.3 to 2.7	
		1.2	1.8 ⁽²⁾	3.5	ns	3.0 to 3.6	
t_w	nCP pulse width HIGH or LOW	3.3	–	–	ns	1.2	see Fig.6, Fig.9
		2.0	–	–	ns	1.65 to 1.95	
		1.6	–	–	ns	2.3 to 2.7	
		1.4	–	–	ns	3.0 to 3.6	
t_{SU}	Set-up time nDn to nCP	0.5	–	–	ns	1.2	see Fig.7, Fig.9
		0.3	–	–	ns	1.65 to 1.95	
		0.2	–	–	ns	2.3 to 2.7	
		0.1	–	–	ns	3.0 to 3.6	
t_h	hold time nDn to nCP	0.5	–	–	ns	1.2	see Fig.7, Fig.9
		0.3	–	–	ns	1.65 to 1.95	
		0.2	–	–	ns	2.3 to 2.7	
		0.1	–	–	ns	3.0 to 3.6	
F_{max}	maximum clock pulse frequency	150	–	–	ns	1.2	see Fig.6, Fig.9
		250	–	–	ns	1.65 to 1.95	
		300	–	–	ns	2.3 to 2.7	
		350	–	–	ns	3.0 to 3.6	

Note

1. All typical values are measured at $T_{amb} = 25$ °C.
2. Typical value is measured at $V_{CC} = 1.8$ V, $V_{CC} = 2.5$ V, $V_{CC} = 3.3$ V.

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AC CHARACTERISTICS 74AVCH16374

 GND = 0 V; $t_r = t_f \leq 2.0$ ns; $C_L = 30$ pF.

SYMBOL	PARAMETER	$T_{amb} = -40$ to $+85$ °C			UNIT	TEST CONDITIONS	
		MIN.	TYP. ⁽¹⁾	MAX.		V_{CC} (V)	WAVEFORMS
t_{PHL}/t_{PLH}	propagation delay nCP to nQ _n	1.6	3.2	5.5	ns	1.2	see Fig.6, Fig.9
		0.9	2.0 ⁽²⁾	4.0	ns	1.65 to 1.95	
		0.8	1.4 ⁽²⁾	2.5	ns	2.3 to 2.7	
		0.7	1.2 ⁽²⁾	2.2	ns	3.0 to 3.6	
t_{PZH}/t_{PZL}	3-state output enable time \overline{nOE}_n to nQ _n				ns	1.2	see Fig.8, Fig.9
					ns	1.65 to 1.95	
					ns	2.3 to 2.7	
					ns	3.0 to 3.6	
t_{PHZ}/t_{PLZ}	3-state output disable time \overline{nOE}_n to nQ _n	–	5.0	–	ns	1.2	see Fig.8, Fig.9
		2.2	3.5 ⁽²⁾	5.0	ns	1.65 to 1.95	
		1.1	1.8 ⁽²⁾	4.0	ns	2.3 to 2.7	
		1.2	1.8 ⁽²⁾	3.5	ns	3.0 to 3.6	
t_w	nCP pulse width HIGH	3.3	–	–	ns	1.2	see Fig.6, Fig.9
		2.0	–	–	ns	1.65 to 1.95	
		1.6	–	–	ns	2.3 to 2.7	
		1.4	–	–	ns	3.0 to 3.6	
t_{SU}	Set-up time nDn to nCP	0.5	–	–	ns	1.2	see Fig.7, Fig.9
		0.3	–	–	ns	1.65 to 1.95	
		0.2	–	–	ns	2.3 to 2.7	
		0.1	–	–	ns	3.0 to 3.6	
t_h	hold time nDn to nCP	0.5	–	–	ns	1.2	see Fig.7, Fig.9
		0.3	–	–	ns	1.65 to 1.95	
		0.2	–	–	ns	2.3 to 2.7	
		0.1	–	–	ns	3.0 to 3.6	
F_{max}	maximum clock pulse frequency	150	–	–	ns	1.2	see Fig.6, Fig.9
		250	–	–	ns	1.65 to 1.95	
		300	–	–	ns	2.3 to 2.7	
		350	–	–	ns	3.0 to 3.6	

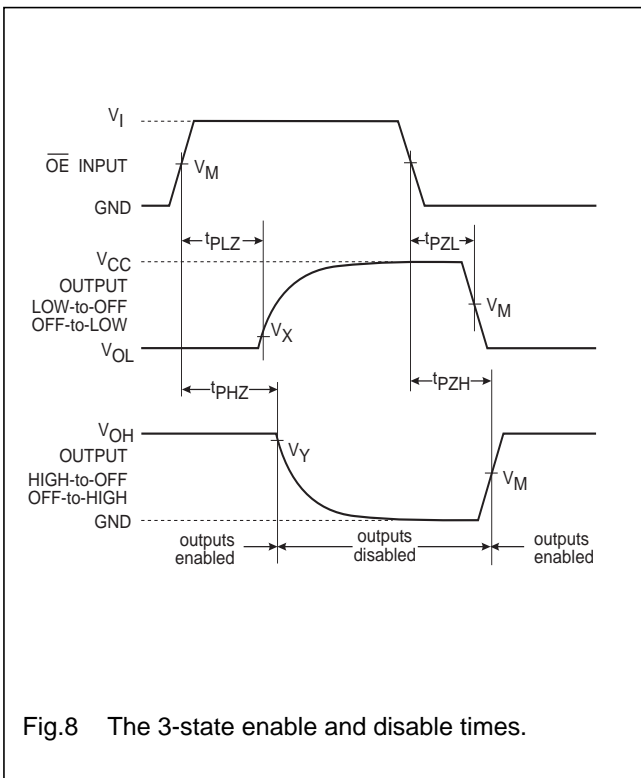
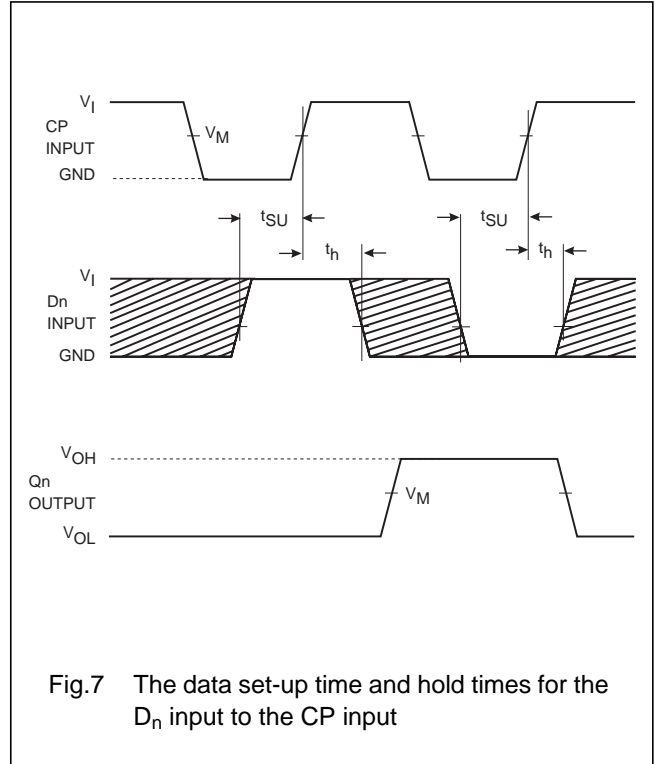
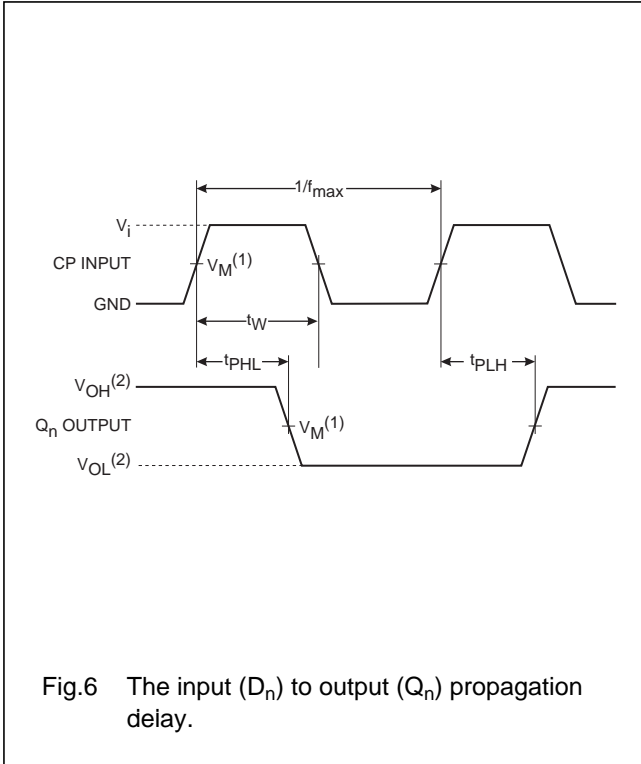
Note

1. All typical values are measured at $T_{amb} = 25$ °C.
2. Typical value is measured at $V_{CC} = 1.8$ V, $V_{CC} = 2.5$ V, $V_{CC} = 3.3$ V.

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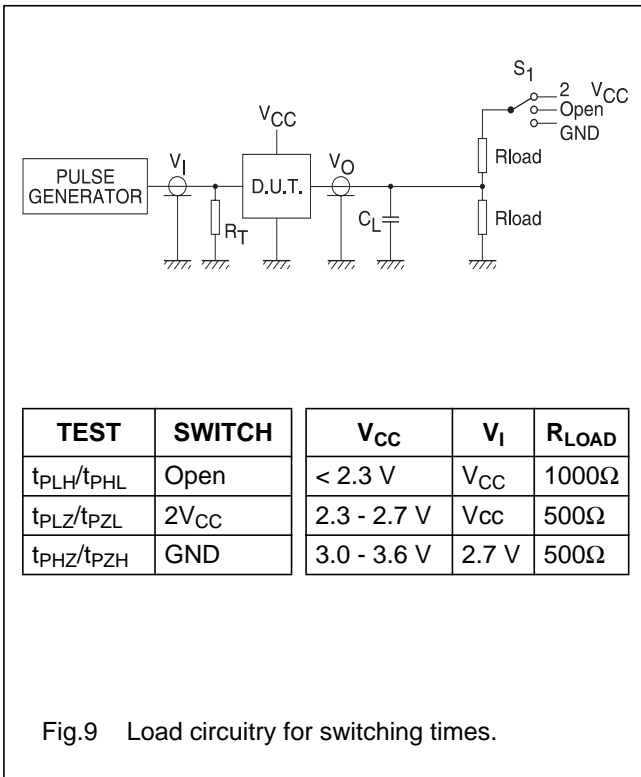
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74AVCH16374**

AC WAVEFORMS



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TEST	SWITCH	V _{CC}	V _I	R _{LOAD}
t _{PLH} /t _{PHL}	Open	< 2.3 V	V _{CC}	1000Ω
t _{PLZ} /t _{PZL}	2V _{CC}	2.3 - 2.7 V	V _{CC}	500Ω
t _{PHZ} /t _{PZH}	GND	3.0 - 3.6 V	2.7 V	500Ω

Fig.9 Load circuitry for switching times.

NOTES: V_{CC} = 2.3 TO 2.7 V RANGE AND V_{CC} < 2.3 V

1. V_M = 0.5V_{CC}
2. V_X = V_{OL} + 150 mV
3. V_Y = V_{OH} - 150 mV
4. V_I = V_{CC}
5. V_{OL} and V_{OH} are typical output voltage drop that occur with the output load.

NOTES: V_{CC} = 3.0 TO 3.6 V RANGE

1. V_M = 0.5V_{CC}
2. V_X = V_{OL} + 300 mV
3. V_Y = V_{OH} - 300 mV
4. V_I = 2.7 V
5. V_{OL} and V_{OH} are typical output voltage drop that occur with the output load.

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PACKAGE OUTLINE

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SOLDERING

Introduction to soldering surface mount packages

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our "Data Handbook IC26; Integrated Circuit Packages" (document order number 9398 652 90011).

There is no soldering method that is ideal for all surface mount IC packages. Wave soldering is not always suitable for surface mount ICs, or for printed-circuit boards with high population densities. In these situations reflow soldering is often used.

Reflow soldering

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several methods exist for reflowing; for example, infrared/convection heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 to 250 °C. The top-surface temperature of the packages should preferably be kept below 230 °C.

Wave soldering

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch (e):
 - larger than or equal to 1.27 mm, the footprint longitudinal axis is **preferred** to be parallel to the transport direction of the printed-circuit board;
 - smaller than 1.27 mm, the footprint longitudinal axis **must** be parallel to the transport direction of the printed-circuit board.

The footprint must incorporate solder thieves at the downstream end.

- For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

Manual soldering

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

Suitability of surface mount IC packages for wave and reflow soldering methods

PACKAGE	SOLDERING METHOD	
	WAVE	REFLOW ⁽¹⁾
BGA, SQFP	not suitable	suitable
HLQFP, HSQFP, HSOP, SMS	not suitable ⁽²⁾	suitable
PLCC ⁽³⁾ , SO, SOJ	suitable	suitable
LQFP, QFP, TQFP	not recommended ⁽³⁾⁽⁴⁾	suitable
SSOP, TSSOP, VSO	not recommended ⁽⁵⁾	suitable

Notes

1. All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the

16-bit edge triggered D-type flip-flop; 3-state

**74AVC16374;
74AVCH16374**

maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the Drypack information in the *"Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods"*.

2. These packages are not suitable for wave soldering as a solder joint between the printed-circuit board and heatsink (at bottom version) can not be achieved, and as solder may stick to the heatsink (on top version).
3. If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.
4. Wave soldering is only suitable for LQFP, TQFP and QFP packages with a pitch (e) equal to or larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.
5. Wave soldering is only suitable for SSOP and TSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.

DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

LIFE SUPPORT APPLICATIONS

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